Tool ID: 209
Tool Location: 107

Equipment Information Sheet

PT770 Etcher - Right Side (III-V)

Manager: Ben Infante 607-254-4813
Backup: Jeremy Clark 607-254-6487

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Chlorine and Methane chemistries used
- User must remain in the lab while tool is in operation

USAGE RESTRICTIONS

- Users must remove photoresist edge bead from full 4 inch wafers.
- pieces must be mounted to sapphire wafer.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 4 hour block reservations anytime. Maximum 12 hours reserved in advance at any time per person. No consecutive research group reservations. Users may use any amount of unreserved time.
- Exceptions may be granted by tool manager.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Photoresist, oxide, nitride, nickel masking only
- Photoresist mask - edge bead must be removed (5mm ring) if using 100mm wafers
- Limited metal masking allowed - see tool manager

Last Updated: 10/14/2026